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(54) Title: PROCESS AND PLANT FOR ELECTRODEPOSITING COPPER

(57) Abstract: The present invention relates to a process for electrochemically winning or refining copper by electrodepositing copper from an electrolyte solution containing the metal in ionogenic form, in which the electrolyte is passed through an electrolysis plant comprising at least one electrolytic cell, which in an electrolyte tank for receiving the electrolyte has at least two electrodes serving as anode and cathode, which are alternately arranged at a distance from each other, and to a corresponding plant. To increase the economic efficiency of such processes and plants, it is proposed in accordance with the invention to immerse the at least one cathode during operation of the electrolysis into the electrolyte over a length of at least 1.2 meters.



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